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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant(s): Douglas Jay Mathews et al.
Assignee: Amkor Technology, Inc. and Tyco Electronics
Logistics AG
Title: MULTI-CHIP SEMICONDUCTOR PACKAGE WITH INTEGRAL
SHIELD AND ANTENNA
Serial No.: 10/621,780 Filed: July 16, 2003
Examiner: Smith, Bradley Group Art 2824
Unit:
Docket No.: G006001

Monterey, CA
December 22, 2004

Mail Stop Amendment
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

AMENDMENT

Dear Sir:

In response to the Office Action dated October 1, 2004,
please amend the above-identified application as follows:

1. **Amendments to the Claims** are reflected in the listing of Claims which begins on page 2 of this paper;
2. **Amendments to the Drawings** begin on page 6 of this paper and include eight replacement sheets (Appendix);
3. **Remarks** begin on page 7 of this paper; and
4. An **Appendix** including eight replacement sheets is attached following page 10 of this paper.